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TOSHIBA Multi-chip Device Silicon PNP Epitaxial Transistor , Field Effect Transistor Silicon N Channel MOS Type

TPCP8F01

Swtching Applications

Load Switch Applications

 Multi-chip discrete device; built-in PNP Transistor for main switch and N-ch MOS FET for drive

• High DC current gain: $h_{FE} = 200 \text{ to } 500 \text{ (IC} = -0.5 \text{ A)}$

(PNP Transistor)

• Low collector-emitter saturation: $V_{CE (sat)} = -0.19 \text{ V (max)}$

(PNP Transistor)

• High-speed switching: tf = 40 ns (typ.) (PNP Transistor)

Absolute Maximum Ratings (Ta = 25°C)

Transistor

Characteristics		Symbol	Rating	Unit	
Collector-base voltage		V _{CBO}	-30	V	
Collector-emitter voltage		V _{CEO}	-20	٧	
Emitter-base voltage		V _{EBO}	-7	V	
Collector current	DC	IC	-3.0	Α	
	Pulse	I _{CP}	-5.0	ζ.	
Base current		I _B	-250	mA	
Collector power dissipation		P _C (Note 1)	1.0	W	
Junction temperature		Tj	150	°C	

Unit: mm ♦ 0.05M A 0.475 B 0.05M B A 0.8±0.05 □ 0.025 S $0.28^{+0.1}_{-0.11}$ $1.12^{+0.13}_{-0.12}$ $1.12_{\,-0.12}^{\,+0.13}$ $0.28^{+0.1}_{-0.11}$ 1.Source 5.Emitter 2.Collector 6.Base 4.Collector **JEDEC** JEITA **TOSHIBA** 2-3V1B

Weight: 0.017g (Typ.)

MOS FET

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	20	V	
Gate-source voltage		V _{GSS}	±10	V	
Drain current	DC	ID	100	mA	
	Pulse	I _{DP}	200	IIIA	
Channel temperature		Tj	150	°C	

Note 1: Mounted on FR4 board (glass epoxy, 1.6mm thick, Cu area: 645mm²)

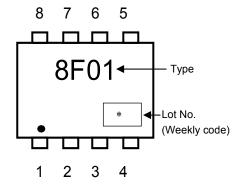
Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Common Absolute Maximum Rating (Ta = 25°C)

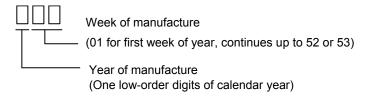
Characteristics	Symbol	Rating	Unit
Storage temperature range	T _{stg}	-55 to 150	°C

Figure 2 Marking (Note 3)



Note 3 : Black round marking " • " located on the left lower side of parts number marking "8F01" indicates terminal No.1

* Weekly code: (Three digits)



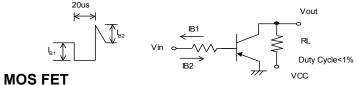
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Electrical Characteristics (Ta = 25°C)

Transistor

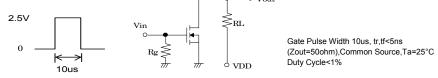
Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current		I _{CBO}	$V_{CB} = -30 \text{ V}, I_{E} = 0$	_	_	-100	nA
Emitter cut-off current		I _{EBO}	$V_{EB} = -7 \text{ V}, I_{C} = 0$	_	_	-100	nA
Collector-emitter breakdown voltage		V (BR) CEO	$I_C = -10 \text{ mA}, I_B = 0$	-20	_	_	V
DC current gain		h _{FE} (1)	$V_{CE} = -2 \text{ V}, I_{C} = -0.5 \text{ A}$	200	_	500	
		h _{FE} (2)	V _{CE} = -2 V, I _C = -1.6 A	100	_	_	
Collector-emitter saturation voltage		V _{CE} (sat)	$I_C = -1.6 \text{ A}, I_B = -53 \text{ mA}$	_	_	-0.19	V
Base-emitter saturation voltage		V _{BE} (sat)	$I_C = -1.6 \text{ A}, I_B = -53 \text{ mA}$	_	_	-1.10	V
Collector Output Capacitance		C _{ob}	V _{CB} = -10 V, I _E = 0, f = 1MHz	_	28	_	pF
Switching time	Rise time	t _r	See Figure 3 circuit diagram $V_{CC} \simeq -12 \text{ V, } R_L = 7.5 \Omega$ $-I_{B1} = I_{B2} = -53 \text{ mA}$	_	70	_	
	Storage time	t _{stg}		_	150	_	ns
	Fall time	t _f		_	40	_	

Figure 3. Switching Time Test Circuit & Timing Chart



Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curre	nt	I _{GSS}	$V_{GS} = -10 \text{ V}, V_{DS} = 0$	_	_	±1	μΑ
Drain-source breakdown voltage		V (BR) DSS	$I_D = 0.1 \text{ mA}, V_{GS} = 0$	20	_	_	V
Drain cut-off curren	t	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0	_	_	1	μΑ
Gate Threshold voltage		V _{th}	$V_{DS} = 3 \text{ V}, I_D = 0.1 \text{ mA}$	0.6	_	1.1	V
Forward Transfer Admittance		Y _{fs}	$V_{DS} = 3 \text{ V}, I_D = 10 \text{ mA}$	40	_	_	mS
Drain-source ON resistance		R _{DS(ON)}	I _D = 10 mA, V _{GS} = 4.0 V	_	1.5	3	Ω
			I _D = 10 mA, V _{GS} = 2.5 V	_	2.2	4	
			I _D = 1 mA, V _{GS} = 1.5 V	_	5.2	15	
Input capacitance		C _{iss}	V _{DS} = 3 V, V _{GS} = 0, f = 1 MHz	_	9.3	_	pF
Reverse transfer capacitance		C _{rss}		_	4.5	_	
Output capacitance		Coss		_	9.8	_	
Switching time	Turn-on time	t _{on}	$V_{DD} \simeq -3 \text{ V, } R_L = 300 \Omega$ $V_{GS} = 0 \text{ to } 2.5 \text{ V}$	_	70	_	ns
	Turn-off time	t _{off}		_	125	_	

Figure 4. Switching Time Test Circuit & Timing Chart

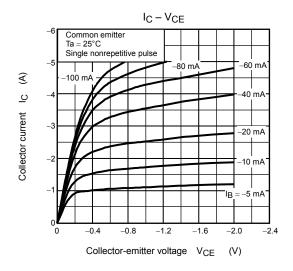


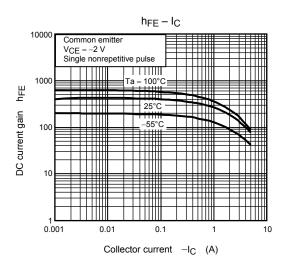
Precautions

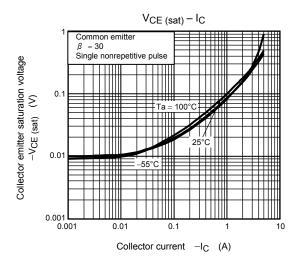
 V_{th} can be expressed as voltage between gate and source when low operating current value is I_D = 100 μ A for this product. For normal switching operation, $V_{GS(ON)}$ requires higher voltage than V_{th} snd $V_{GS(OFF)}$ requires lower voltage than V_{th} . (relationship can be established as follows: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$) Please take this into consideration for using the device.

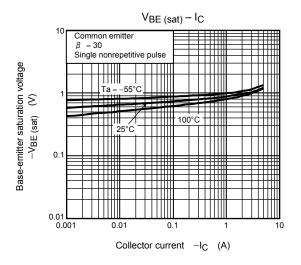
VGS recommended voltage of 2.5V or higher to turn on this product.

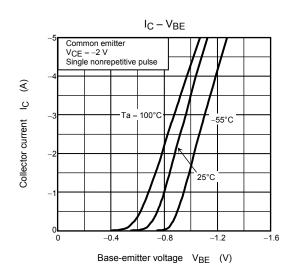
PNP

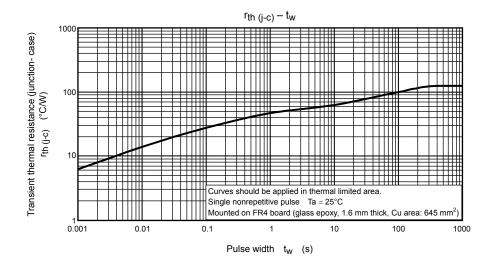


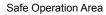


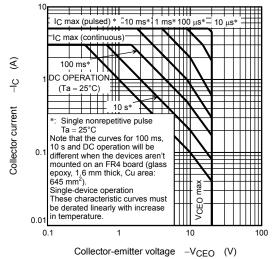




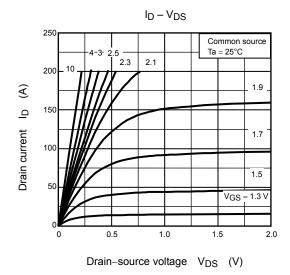


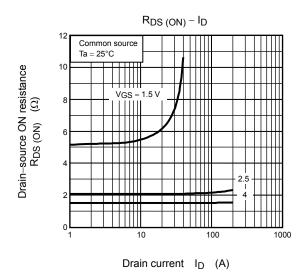


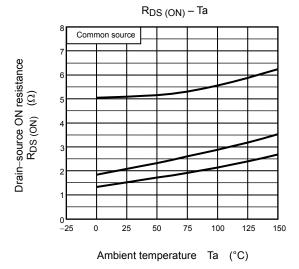


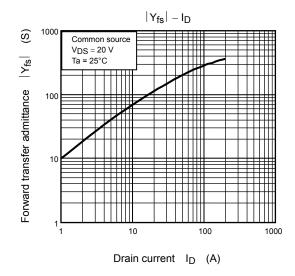


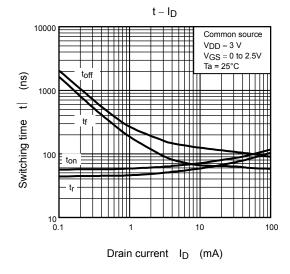
Nch-MOS

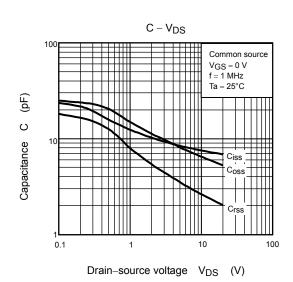




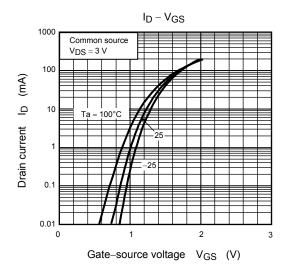


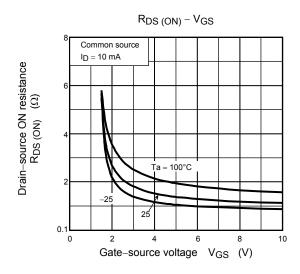


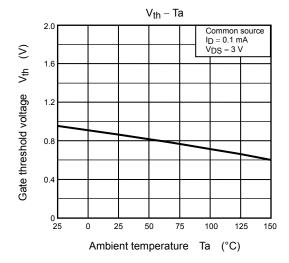


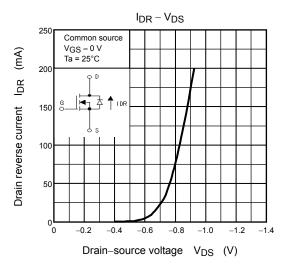


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